

Class H

- 3.2.1.1 b. Scratch in the bonding pad area that both exposes underlying material and reduces the metallization path width, where it enters the bonding pad, to less than 50 percent its original metallization width. If two or more metallization paths enter a bonding pad, each shall be considered separately (see figure 2032-39h).

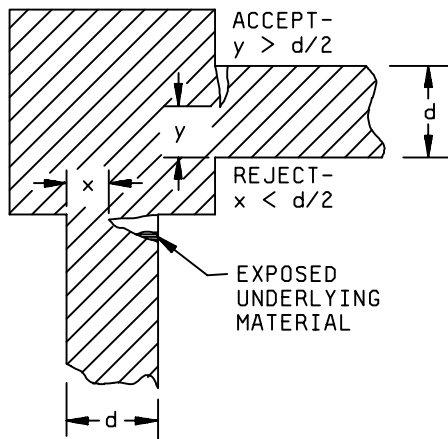


FIGURE 2032-39h. Class H metallization width reduction at bonding pad criteria.

Class K

- 3.2.1.1 b. Less than 75 percent (see figure 2032-39k).

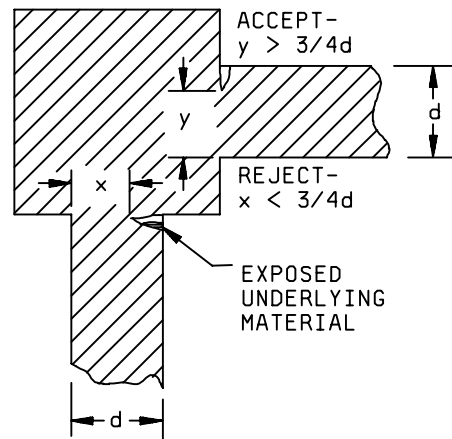


FIGURE 2032-39k. Class K metallization width reduction at bonding pad criteria.

- c. Scratch or probe marks in the bonding pad area that expose underlying material over more than 25 percent of the original metallization area.

- c. Same as class H